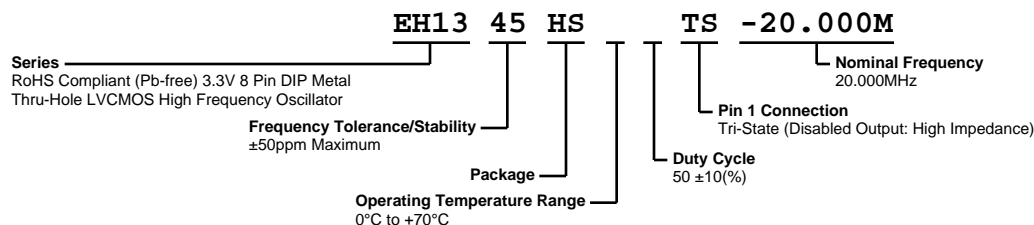


# EH1345HSTS-20.000M



**ECLIPTEK**  
CORPORATION



## ELECTRICAL SPECIFICATIONS

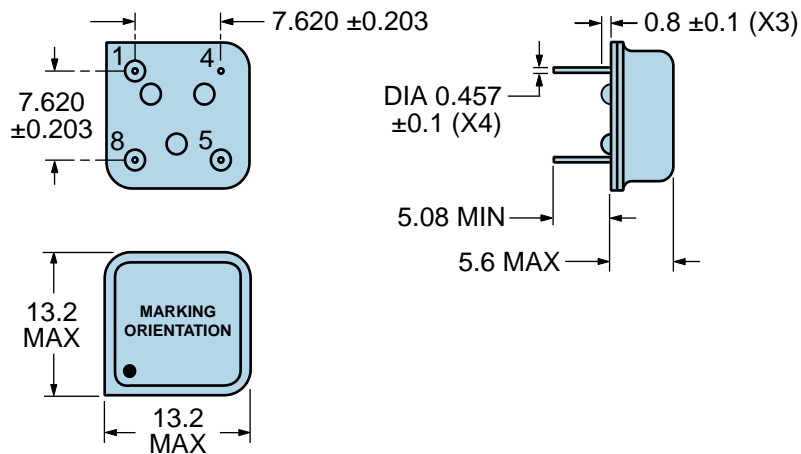
Nominal Frequency	20.000MHz
Frequency Tolerance/Stability	$\pm 50\text{ppm}$ Maximum (Inclusive of all conditions: Calibration Tolerance at $25^{\circ}\text{C}$ , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, 1st Year Aging at $25^{\circ}\text{C}$ , Shock, and Vibration.)
Aging at $25^{\circ}\text{C}$	$\pm 5\text{ppm/year}$ Maximum
Operating Temperature Range	$0^{\circ}\text{C}$ to $+70^{\circ}\text{C}$
Supply Voltage	3.3Vdc $\pm 0.3\text{Vdc}$
Input Current	35mA Maximum (No Load)
Output Voltage Logic High (Voh)	2.7Vdc Minimum ( $\text{IOH} = -8\text{mA}$ )
Output Voltage Logic Low (Vol)	0.5Vdc Maximum ( $\text{IOL} = +8\text{mA}$ )
Rise/Fall Time	6nSec Maximum (Measured at 20% to 80% of waveform)
Duty Cycle	$50 \pm 10(\%)$ (Measured at 50% of waveform)
Load Drive Capability	30pF Maximum
Output Logic Type	CMOS
Pin 1 Connection	Tri-State (Disabled Output: High Impedance)
Tri-State Input Voltage (Vih and Vil)	70% of Vdd Minimum to enable output, 20% of Vdd Maximum to disable output (High Impedance), No Connect to enable output.
Absolute Clock Jitter	$\pm 250\text{pSec}$ Maximum, $\pm 100\text{pSec}$ Typical
One Sigma Clock Period Jitter	$\pm 50\text{pSec}$ Maximum, $\pm 40\text{pSec}$ Typical
Start Up Time	10mSec Maximum
Storage Temperature Range	$-55^{\circ}\text{C}$ to $+125^{\circ}\text{C}$

## ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

Fine Leak Test	MIL-STD-883, Method 1014, Condition A
Gross Leak Test	MIL-STD-883, Method 1014, Condition C
Lead Integrity	MIL-STD-883, Method 2004
Mechanical Shock	MIL-STD-202, Method 213, Condition C
Resistance to Soldering Heat	MIL-STD-202, Method 210
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003
Temperature Cycling	MIL-STD-883, Method 1010
Vibration	MIL-STD-883, Method 2007, Condition A

# EH1345HSTS-20.000M

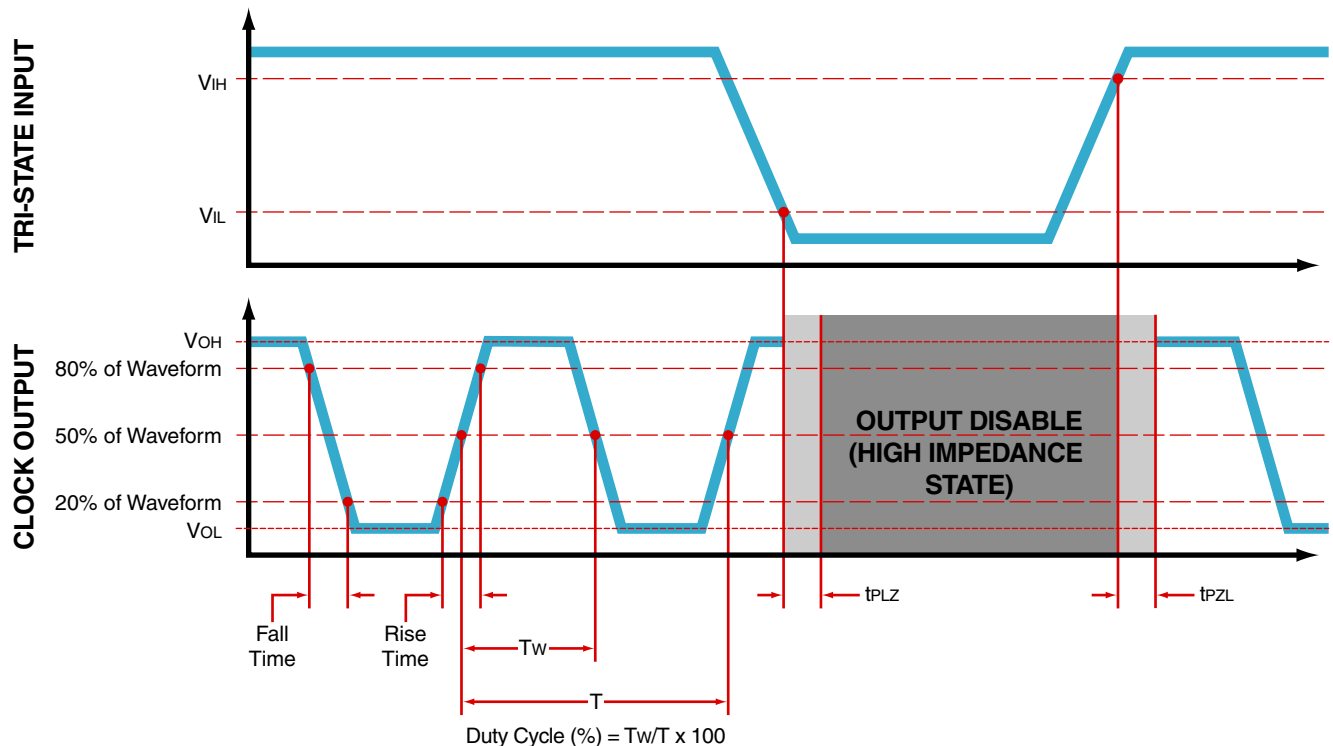
## MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State (High Impedance)
4	Case/Ground
5	Output
8	Supply Voltage

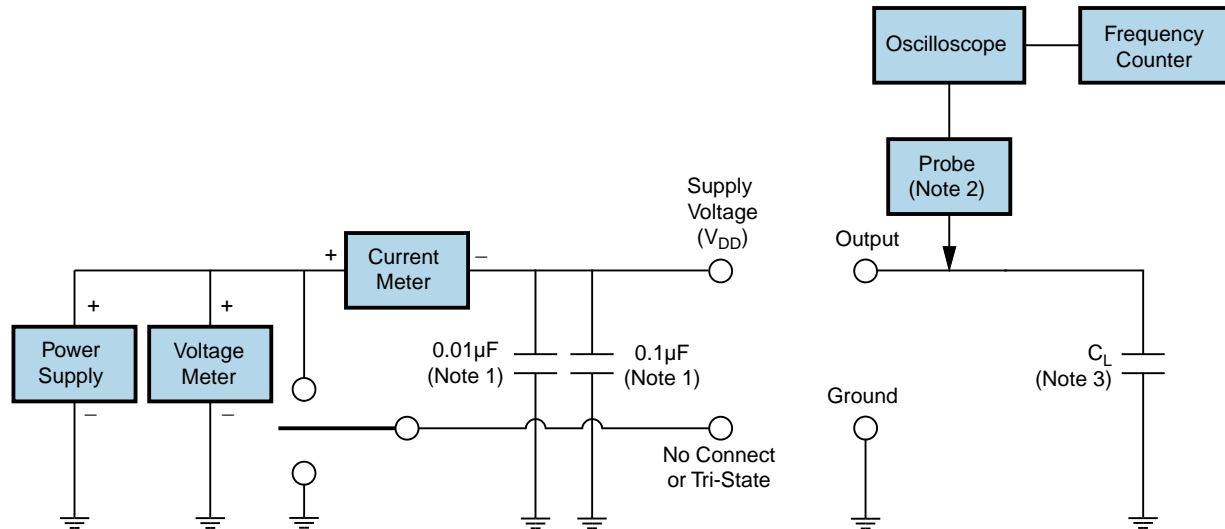
LINE	MARKING
1	<b>ECLIPTEK</b>
2	<b>EH13TS</b> EH13=Product Series
3	<b>20.000M</b>
4	<b>XXYYZZ</b> XX=Ecliptek Manufacturing Code Y=Last Digit of the Year ZZ=Week of the Year

## OUTPUT WAVEFORM & TIMING DIAGRAM



# EH1345HSTS-20.000M

## Test Circuit for CMOS Output

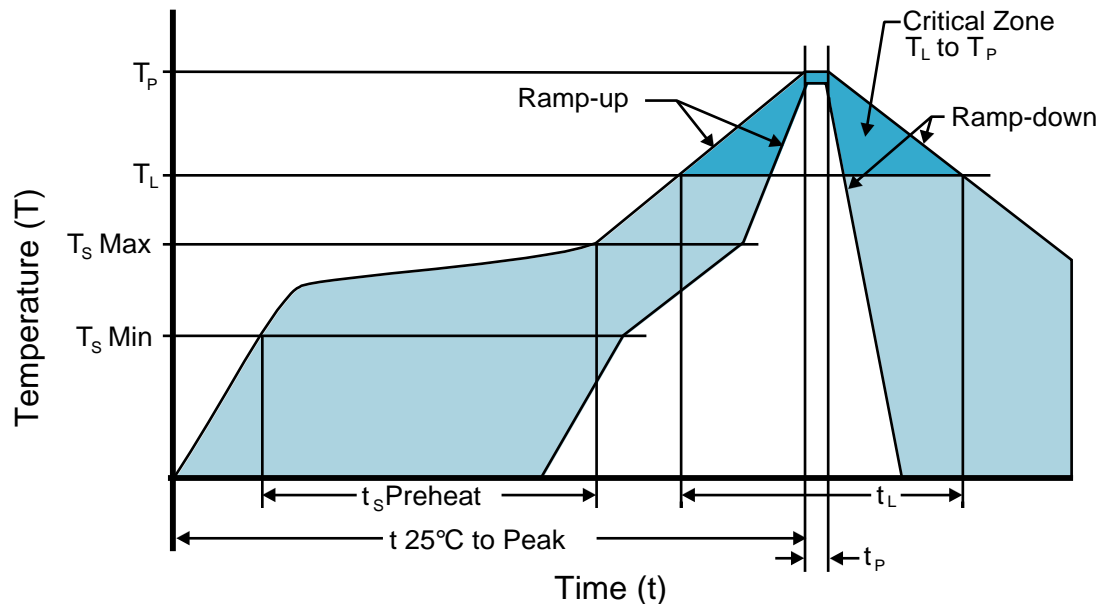


Note 1: An external  $0.1\mu F$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu F$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12pF$ ), 10X attenuation factor, high impedance ( $>10M\Omega$ ), and high bandwidth ( $>300MHz$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

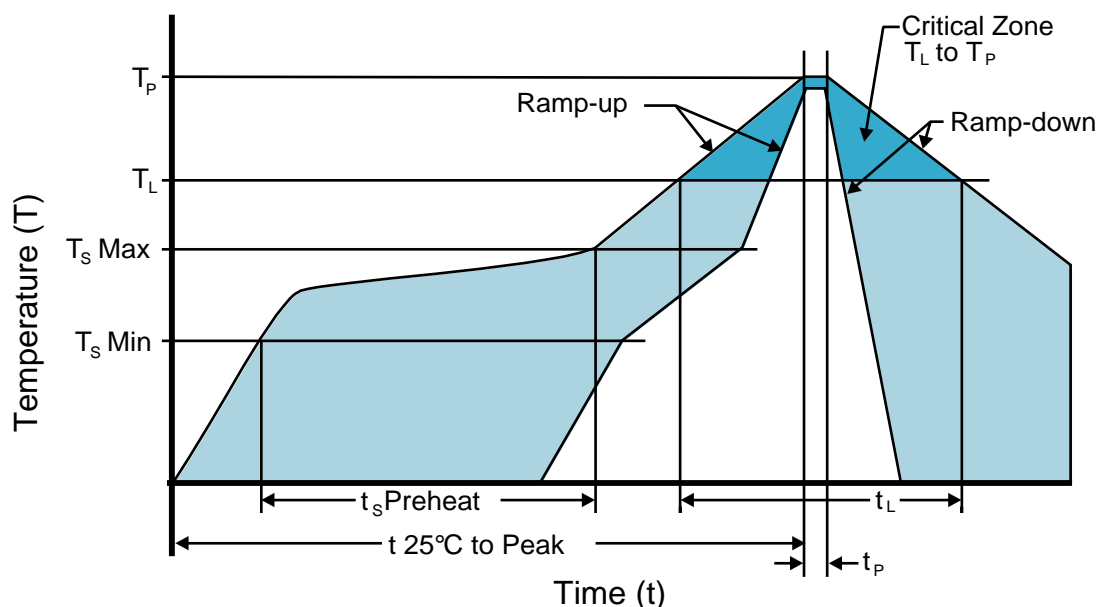
## Recommended Solder Reflow Methods



### High Temperature Solder Bath (Wave Solder)

$T_s \text{ MAX to } T_L$ (Ramp-up Rate)	3°C/second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_s \text{ MIN}$ )	150°C
- Temperature Typical ( $T_s \text{ TYP}$ )	175°C
- Temperature Maximum ( $T_s \text{ MAX}$ )	200°C
- Time ( $t_s \text{ MIN}$ )	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_p</math>)</b>	3°C/second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_p</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_p \text{ Target}</math>)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 seconds
<b>Ramp-down Rate</b>	6°C/second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 185°C

<b><math>T_s</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	5°C/second Maximum
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#### Preheat

- Temperature Minimum ( $T_s$ MIN)	N/A
- Temperature Typical ( $T_s$ TYP)	150°C
- Temperature Maximum ( $T_s$ MAX)	N/A
- Time ( $t_s$ MIN)	60 - 120 Seconds

<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	5°C/second Maximum
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#### Time Maintained Above:

- Temperature ( $T_L$ )	150°C
- Time ( $t_L$ )	200 Seconds Maximum

<b>Peak Temperature (<math>T_P</math>)</b>	185°C Maximum
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<b>Target Peak Temperature (<math>T_P</math> Target)</b>	185°C Maximum 2 Times
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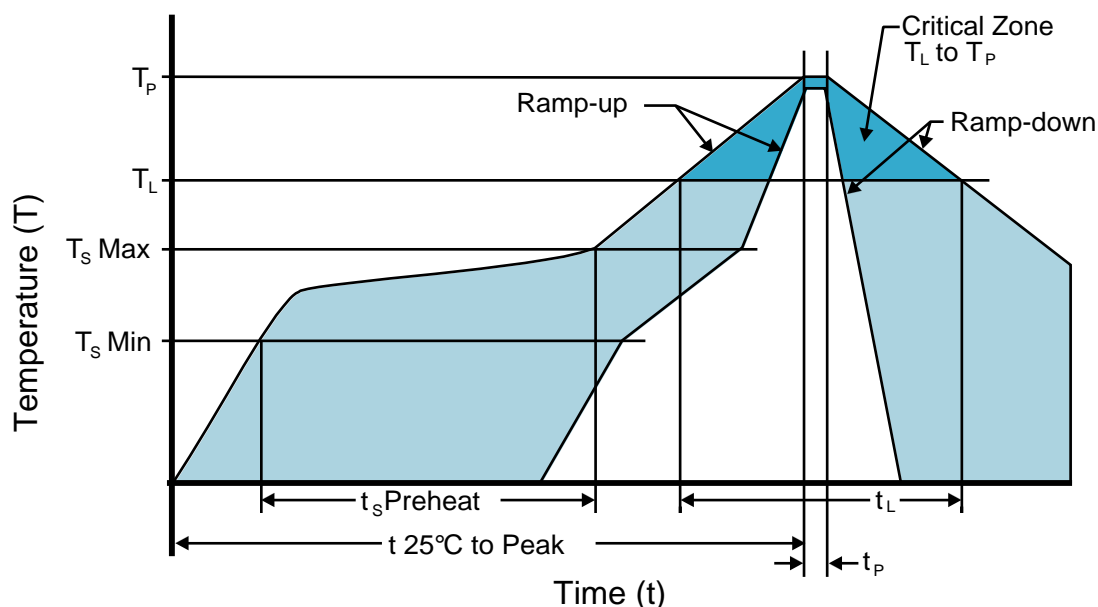
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	10 seconds Maximum 2 Times
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<b>Ramp-down Rate</b>	5°C/second Maximum
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<b>Time 25°C to Peak Temperature (t)</b>	N/A
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<b>Moisture Sensitivity Level</b>	Level 1
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## Recommended Solder Reflow Methods



### Low Temperature Solder Bath (Wave Solder)

$T_S$  MAX to  $T_L$  (Ramp-up Rate) 5°C/second Maximum

#### Preheat

- Temperature Minimum ( $T_S$  MIN) N/A  
 - Temperature Typical ( $T_S$  TYP) 150°C  
 - Temperature Maximum ( $T_S$  MAX) N/A  
 - Time ( $t_s$  MIN) 30 - 60 Seconds

Ramp-up Rate ( $T_L$  to  $T_P$ ) 5°C/second Maximum

#### Time Maintained Above:

- Temperature ( $T_L$ ) 150°C  
 - Time ( $t_L$ ) 200 Seconds Maximum

Peak Temperature ( $T_P$ ) 245°C Maximum

Target Peak Temperature ( $T_P$  Target) 245°C Maximum 1 Time / 235°C Maximum 2 Times

Time within 5°C of actual peak ( $t_p$ ) 5 seconds Maximum 1 Time / 15 seconds Maximum 2 Times

Ramp-down Rate 5°C/second Maximum

Time 25°C to Peak Temperature (t) N/A

Moisture Sensitivity Level Level 1

### Low Temperature Manual Soldering

185°C Maximum for 10 seconds Maximum, 2 times Maximum.

### High Temperature Manual Soldering

260°C Maximum for 5 seconds Maximum, 2 times Maximum.